



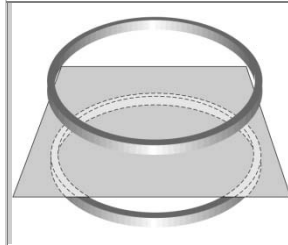
Hoop Sets, Mylar™, Adhesive Tape & Diamond Scribe Tools

Diamond Scribe Tools



Scribe tools are the essence of dry process dicing. Dynatex International diamond scribe tools are manufactured to a precision standard with close geometric tolerances. This translates directly into consistent scribing and ultimately high yield in the production environment.

Low Tack Tape



Low tack tape is used to mount wafers for back end processes. Available in precut squares or rolls this medium is ideal for the saw dicing and scribe and break process. The low tack nature of the tape facilitates pick and place of the smallest die. Another feature of this product is the ability to stretch. This allows the user to "expand" the diced wafer creating additional space between adjacent die, thereby simplifying the pick and place process.

Hoops



Wafer handling systems are an integral part of establishing optimum yield. They minimize loss and maximize efficiency. Dynatex's hoop set and adhesive tape forms a carrier and handling frame for wafers. The hoop sets are reusable and available in many different sizes.

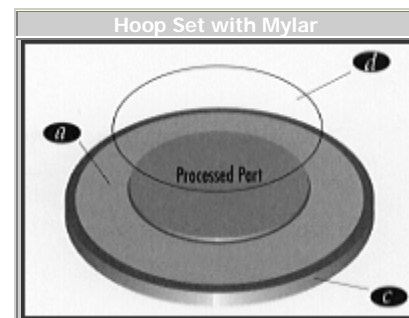
Hoop Carriers



Dynatex Hoop Set with Mylar

The diagram on the right shows the components of our Wafer Handling System:

- a. Adhesive Material
- c. Outer Hoop
- d. Mylar Overlay



The Adhesive is placed with the Outer Hoop beneath it and the Inner Hoop above

Using the DXE Wafer Expander, the Hoops stretch the adhesive like a drum skin. The Wafer is then placed on the adhesive surface and covered with the mylar. The mylar overlay protects the wafer from dust and contaminants.